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Shengli Wu

Yiwei Liu

Xiaoning Zhang

Can Yang

Lingguang Liu

See next page for additional authors

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Authors

Shengli Wu, Yiwei Liu, Xiaoning Zhang, Can Yang, Lingguang Liu, Yaogong Wang, and Gang Niu





Performance Enhancement of Solid State Light Emission Device and Geometrically Confinement of Lighting Dots by Using Patterned Wafer Approaches

<u>Shengli Wu*,</u> Yiwei Liu, Xiaoning Zhang, Can Yang, Lingguang Liu, Yaogong Wang and Gang Niu *Email: slwu@mail.xjtu.edu.cn

Key Lab. for Physical Electronics and Devices of the Ministry of Education, Xi'an Jiaotong University, Xi'an, China





Outline

Background & Motivation

- Effect of Si substrate in SSI-LED
- SSI-LED on patterned Si-substrate

• Summary





> Light source requirement for grating displacement sensor

- Continuous spectrum
- Small in size
- Light in weight

Typical source used before:

Tungsten Halogen Lamp





Conventional LED



(Shuji Nakamura, et al. Appl. Phys. Lett. 1994)



(E. Fred Schubert, et al. Science 2005)

Obtain white light

- Blue LED+Yellow phosphor
- R+G+B LEDs

Disadvantages

- Complicated structure
- Narrow light spectrum (peaks)
- Low light intensity at red side



> Improvement of Luminescence spectrum for LED



- Small in size
- Light in weight



Mr.

Luminescence spectrum need to be improved



LED lamp & Its spectrum after adjusting the ratio of red phosphor

Solid State Incandescent Light Emitting Device (SSI-LED)



MOS structure

- Broad band spectrum
- Light emission layer:
 - ✓ HfO₂ (key material)
 - ✓ HfO₂ + other materials





> Mechanism of SSI-LED





2313

(Y Kuo, et al. Solid State Electronics. 2013) (Y Kuo, et al. Appl. Phys. Lett. 2015)

Luminescence comes from thermal excitation of current flowing through conductive filaments (CF).



> Mechanism of SSI-LED



(Y Liu, et al. Nanotechnology. 2017)

The conductive material in the pits is the conductive filament.



> SSI-LED vs LED



Advantages of SSI-LEDs

- Simple MOS capacitor structure
- Light emission spectrum: from visible to IR ranges
- Low cost
- IC compatible processes



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Fabrication process of SSI-LED

- Substrate cleaning: BOE solution (60s); acetone(5min); ethyl alcohol(5min)
- ► High-k layer: Sputtering Hf target, Ar:O₂=20:20, 100W, RT, 600 s
- ► ITO electrode: Sputtering ITO target, Ar:O₂=20:0, 70W, RT, 600 s
- ITO etching: aqua regia, 20s
- ► RTA: N₂, 400°C, 5min





Effect of Si substrate doping type (p-Si & n-Si)

• Characteristics of light emission



- ✓ More lighting dots in p-Si device
- ✓ Brighter light generated in p-Si device





J-V curve

• Electrical properties

J-V curve



p-Si substrate:

- ✓ Lower breakdown and working voltage
- $\checkmark\,$ More suitable for SSI-LED than n-Si



Effect of Si substrate in SSI-LED





Effect of Si substrate in SSI-LED

Effect of doping concentrations of Si substrate



✓ P-10¹⁵ cm⁻³ is the optimization parameter of Si substrate for SSI-LED.



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> Si substrates patterned in 2 different process

Electric field applied on HfO₂ can be enhanced by the patterned wafer

Wet-etching process

Tetramethylammonium Hydroxide (TMAH) solution at room temperature by standing wet-etching. (distribution cannot be controlled)

CVD Si (001) CVD Si (001)

Si tips: Advanced lithography and reaction-ion-etching technologies

SiO₂ layer: CVD method

Stripes: Chemical mechanical polishing process



> Si substrate patterned randomly using wet-etching process (1)

• Device structure



> Si substrate patterned randomly using wet-etching process (2)

• Electrical characteristic



J-V curves of the nano-pinnacles substrate and reference device

The nano-pinnacles substrate device has a lower breakdown voltage and larger working current density than the reference device.

1223

> Si substrate patterned randomly using wet-etching process (3)

Optical characteristic



Lighting spectrum and photo of the nano-pinnacles substrate and reference device

Lighting dot density:

 0.8×10^{3} /cm² (reference device) and 6.9×10^{3} /cm² (nano-pinnacles device)

More lighting dots and brighter in nano-pinnacles substrate device.

> Si substrate patterned regularly using CMOS processing (1)

HfO₂

• Device structure



SEM image



> Si substrate patterned regularly using CMOS processing (2)

• Electrical characteristic



J-V curves of the nano-stripe substrate and reference device

Nano-stripe device can breakdown and work under lower voltage.

> Si substrate patterned regularly using CMOS processing (3)

Optical characteristic



Reference sample

Nano-stripe device

Lighting photo of the nano-stripe substrate and reference device

Lighting dot density: 2.66×10^{6} /cm² vs 2.02×10^{7} /cm² Lighting dots still distribute in a random way.

> Si substrate patterned regularly using CMOS processing (4)

• Optical characteristic



Lighting spectra of nano-stripe and reference device

The properties of SSI-LED are improved by using nano-stripe substrate Distribution of lighting dots still can not be controlled.

> Si substrate patterned regularly using CMOS processing (5)

• Micrometer size stripe substrate device



> Si substrate patterned regularly using CMOS processing (6)

• Micrometer size stripe substrate device



Before lighting



lighting

Lighting photos of the micrometer size stripe substrate device



> Si substrate patterned regularly using CMOS processing (6)

• Micrometer size stripe substrate device





Lighting photo of the micrometer size cylinder substrate and reference device

Generally conductive filaments appear randomly. For devices fabricated on substrates with micrometer size structure, the arrangement of bright dots coincides with the nanostructure array on the substrate.



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- The doping type and concentration of Si substrate has significant effects on performance of the device. The p-10¹⁵ cm⁻³ Si wafer is a superior substrate candidate for the SSI-LEDs.
- The electrical and optical characteristics of SSI-LED were optimized with the use of two nanometer size structures, nano-pyramid and nano-stripe, fabricated on Si substrate.
- The surface structure patterned regularly on substrate with a micro-meter size has been verified to be in great capacity for the lighting dots distribution control.





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Thank you for your kind attention!

